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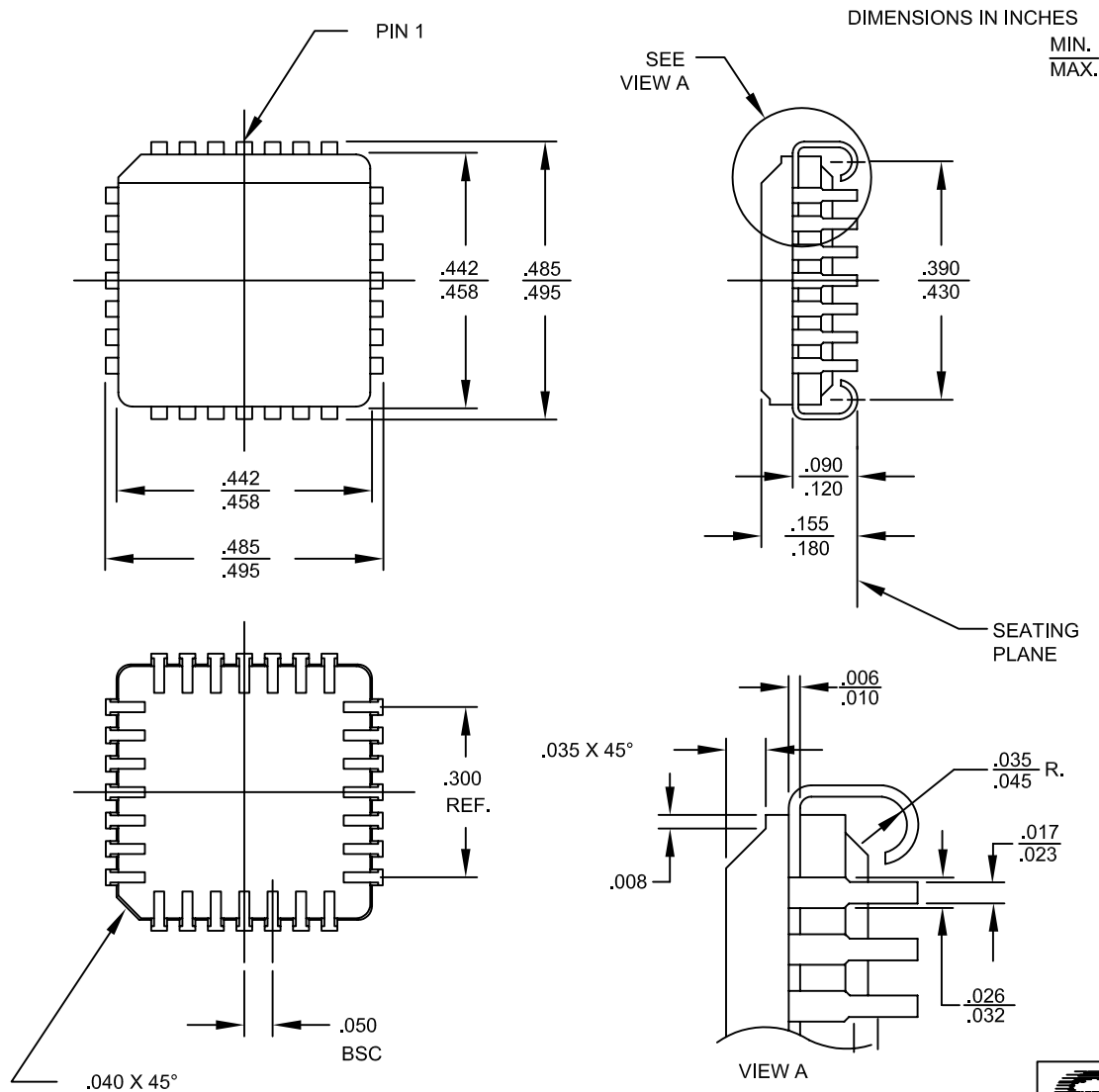
Continuity of document content

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Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

28-Pin Ceramic Leaded Chip Carrier Y64



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PACKAGE
CODE(S)



CYPRESS
Company Confidential

TITLE
PACKAGE OUTLINE, 28L CLCC 0.45X0.45 IN. Y28

SPEC NO.
51-80092

REV
*C


SCALE

SHEET 1 OF 2

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